

## MWC Round-Up, Preview

The following consolidates the flurry of information associated with the Mobile World Congress in Barcelona next week. Below are press releases from companies in the Tokeneke semiconductor Universe posted over the last week specifically related to that gathering with hyperlinks to the documents via Yahoo!Finance. Companies are obviously jumping the gun before the show to get visibility ahead of the crush, and some appear to be double-dipping with announcements originally disclosed at CES in January.

**AMD**

[AMD Aims to Meet Higher Expectations for Tablet and Hybrid PC Performance at Mobile World Congress 2013](#)

**BRCM**

[Broadcom Introduces GNSS Location Chip with Geofence Capabilities](#)

**CEVA**

[CEVA and Sensory Partner to Deliver Lowest Power Voice Activation Solution Based on CEVA-TeakLite-4 DSP Platform](#)

[CEVA and Mindspeed Extend Relationship to Address LTE-Advanced Small Cells](#)

[CEVA Introduces MUST™ Multi-core System Technology, Adds Vector Floating-point Capabilities for CEVA-XC DSP](#)

[CEVA to Showcase Industry-Leading Platform IP for Communications, Vision, Imaging, Audio and Voice at MWC 2013](#)

**ERIC(/STM)**

[ST-Ericsson brings PC speeds to mobile devices: First 3Ghz smartphone prototype demo at Mobile World Congress](#)

**IDTI**

[IDT Announces Data Compression IP Offering Industry's Highest Performance for 3G and 4G Wireless Infrastructure Apps](#)

[IDT to Exhibit Industry-Leading Products at Mobile World Congress and IIC China](#)

**INVN**

[InvenSense® to Exhibit at Mobile World Congress 2013](#)

**FCS**

[Fairchild Semiconductor to Focus on Enriched User Experiences at Mobile World Congress 2013](#)

**LSI**

[LSI Introduces Axxia® 5500 Communication Processors with ARM Technology for High-Perf. Power-Efficient Networks](#)

**MRVL**

[Marvell Announces Industry's Most Advanced Single-chip Quad-core World Phone Processor to Power High-performance, Smartphones and Tablets with Worldwide Automatic Roaming on 3G Networks](#)

[Marvell's Quad-core LTE Platform Will be In Production this Year with Dual Radio Dual Standby and Circuit Switch Fall Back](#)

**MSPD**

[Mindspeed to Highlight New Customers, New Products and Leadership in Small Cell Market at Mobile World Congress 2013](#)

[Radisys and Mindspeed Continue Small Cell Leadership with Industry's First LTE-A Small Cell Demonstration](#)

[InterDigital, Mindspeed and Radisys Collaborate to Deliver Integrated Small Cell with Wi-Fi Solution](#)

[Mindspeed Announces Next Generation Transcede SoCs for Metro and Premium Enterprise Small Cell Applications](#)

**MXIM**

[Maxim Integrated Collaborates with Freescale to Showcase a Comprehensive Outdoor LTE Picocell at Mobile World Congress](#)

[LTE/3G Multimode RF Transceiver from Maxim Integrated Enables Successful Deployment of HetNet Small Cell Base Stations](#)

**NVDA**

[NVIDIA Introduces Its First Integrated Tegra LTE Processor](#)

**NXPI**

[NXP Strengthens SmartMX2 Security Chips With PUF Anti-Cloning Technology](#)

**QCOM**

[Qualcomm RF360 Front End Solution Enables Single, Global LTE Design for Next-Generation Mobile Devices](#)

[Qualcomm Kicks Off Wireless Walking Challenge with the American Heart Association at Mobile World Congress 2013](#)

**RFMD**

[RFMD\(R\) to Showcase Industry-Leading Products and Technologies at 2013 Mobile World Congress](#)

**SIMG**

[MHL Consortium to Showcase Industry-Leading Mobile HD Connectivity Technology at 2013 Mobile World Congress](#)

**TQNT**

[TriQuint Enables Gigabit Wi-Fi and 4G Coexistence For Next-Generation Smartphones and Tablets](#)

[TriQuint Harnesses Its Advanced Filter Tech to Debut High-Perf Duplexer Bank for Toughest 3G / 4G Smartphone Bands](#)

[TriQuint's New High-Efficiency MMPAs Extend Connectivity Time for Next-Gen Global 3G / 4G Smartphones](#)

**TSRA**

[DigitalOptics Corporation Launches memscam™](#)

**XLNX**

[Xilinx and TEKTELIC Reduce Cellular Radio Infrastructure Development Time with Scalable IP and High Perf Transceiver](#)

[Xilinx Launches Fully Adaptive Gbps Class Point-to-Point Microwave Modem IP for Backhaul Applications](#)

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